

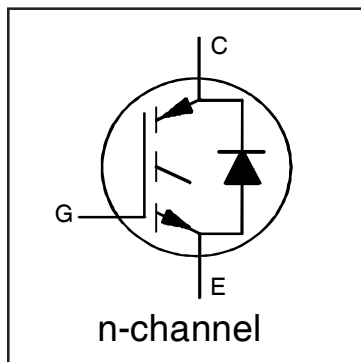
### INSULATED GATE BIPOLAR TRANSISTOR WITH ULTRAFAST SOFT RECOVERY DIODE

#### Features

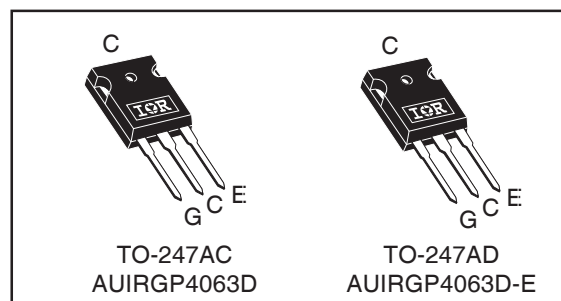
- Low  $V_{CE(ON)}$  Trench IGBT Technology
- Low switching losses
- Maximum Junction temperature 175 °C
- 5  $\mu$ S short circuit SOA
- Square RBSOA
- 100% of the parts tested for 4X rated current ( $I_{LM}$ )
- Positive  $V_{CE(ON)}$  Temperature co-efficient
- Ultra fast soft Recovery Co-Pak Diode
- Tight parameter distribution
- Lead Free Package

#### Benefits

- High Efficiency in a wide range of applications
- Suitable for a wide range of switching frequencies due to Low  $V_{CE(ON)}$  and Low Switching losses
- Rugged transient Performance for increased reliability
- Excellent Current sharing in parallel operation
- Low EMI



$V_{CES} = 600V$
$I_C = 60A, T_C = 100^\circ C$
$t_{SC} \geq 5\mu s, T_{J(max)} = 175^\circ C$
$V_{CE(on)} \text{ typ.} = 1.6V$



<b>G</b>	<b>C</b>	<b>E</b>
Gate	Collector	Emitter

Base part number	Package Type	Standard Pack		Orderable Part Number
		Form	Quantity	
AUIRGP4063D	TO-247	Tube	25	AUIRGP4063D
AUIRGP4063D-E	TO-247	Tube	25	AUIRGP4063D-E

#### Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature ( $T_A$ ) is 25°C, unless otherwise specified.

	Parameter	Max.	Units
$V_{CES}$	Collector-to-Emitter Voltage	600	V
$I_C @ T_C = 25^\circ C$	Continuous Collector Current	100	A
$I_C @ T_C = 100^\circ C$	Continuous Collector Current	60	
$I_{CM}$	Pulse Collector Current, $V_{GE} = 15V$	144	
$I_{LM}$	Clamped Inductive Load Current, $V_{GE} = 20V$ ①	192	
$I_F @ T_C = 25^\circ C$	Diode Continuous Forward Current	82	
$I_F @ T_C = 100^\circ C$	Diode Continuous Forward Current	50	
$I_{FM}$	Diode Maximum Forward Current ②	192	V
$V_{GE}$	Continuous Gate-to-Emitter Voltage	$\pm 20$	
	Transient Gate-to-Emitter Voltage	$\pm 30$	
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	330	W
		$P_D @ T_C = 100^\circ C$	
$T_J$ $T_{STG}$	Operating Junction and Storage Temperature Range	-55 to +175	°C
	Soldering Temperature, for 10 sec.	300 (0.063 in. (1.6mm) from case)	
	Mounting Torque, 6-32 or M3 Screw	10 lbf-in (1.1 N·m)	

**Thermal Resistance**

	Parameter	Min.	Typ.	Max.	Units
R <sub>θJC</sub> (IGBT)	Thermal Resistance Junction-to-Case-(each IGBT)	—	—	0.45	°C/W
R <sub>θJC</sub> (Diode)	Thermal Resistance Junction-to-Case-(each Diode)	—	—	0.92	
R <sub>θCS</sub>	Thermal Resistance, Case-to-Sink (flat, greased surface)	—	0.24	—	
R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient (typical socket mount)	—	80	—	

**Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)**

	Parameter	Min.	Typ.	Max.	Units	Conditions	Ref. Fig
V <sub>(BR)CES</sub>	Collector-to-Emitter Breakdown Voltage	600	—	—	V	V <sub>GE</sub> = 0V, I <sub>C</sub> = 150μA ④	CT6
$\frac{dV_{(BR)CES}}{dT_J}$	Temperature Coeff. of Breakdown Voltage	—	0.30	—	V/°C	V <sub>GE</sub> = 0V, I <sub>C</sub> = 1mA (25°C-175°C)	CT6
V <sub>CE(on)</sub>	Collector-to-Emitter Saturation Voltage	—	1.6	1.9	V	I <sub>C</sub> = 48A, V <sub>GE</sub> = 15V, T <sub>J</sub> = 25°C	5.6,7
		—	1.9	—		I <sub>C</sub> = 48A, V <sub>GE</sub> = 15V, T <sub>J</sub> = 150°C	9,10,11
		—	2.0	—		I <sub>C</sub> = 48A, V <sub>GE</sub> = 15V, T <sub>J</sub> = 175°C	
V <sub>GE(th)</sub>	Gate Threshold Voltage	4.0	—	6.5	V	V <sub>CE</sub> = V <sub>GE</sub> , I <sub>C</sub> = 1.4mA	9, 10,
$\frac{dV_{GE(th)}}{dT_J}$	Threshold Voltage temp. coefficient	—	-21	—	mV/°C	V <sub>CE</sub> = V <sub>GE</sub> , I <sub>C</sub> = 1.0mA (25°C - 175°C)	11, 12
g <sub>fe</sub>	Forward Transconductance	—	32	—	S	V <sub>CE</sub> = 50V, I <sub>C</sub> = 48A, PW = 80μs	
I <sub>CES</sub>	Collector-to-Emitter Leakage Current	—	1.0	150	μA	V <sub>GE</sub> = 0V, V <sub>CE</sub> = 600V	
		—	450	1000		V <sub>GE</sub> = 0V, V <sub>CE</sub> = 600V, T <sub>J</sub> = 175°C	
V <sub>FM</sub>	Diode Forward Voltage Drop	—	1.95	2.91	V	I <sub>F</sub> = 48A	8
		—	1.45	—		I <sub>F</sub> = 48A, T <sub>J</sub> = 175°C	
I <sub>GES</sub>	Gate-to-Emitter Leakage Current	—	—	±100	nA	V <sub>GE</sub> = ±20V	

**Switching Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)**

	Parameter	Min.	Typ.	Max.	Units	Conditions	Ref. Fig
Q <sub>g</sub>	Total Gate Charge (turn-on)	—	95	140	nC	I <sub>C</sub> = 48A	24
Q <sub>ge</sub>	Gate-to-Emitter Charge (turn-on)	—	28	42		V <sub>GE</sub> = 15V	CT1
Q <sub>gc</sub>	Gate-to-Collector Charge (turn-on)	—	35	53		V <sub>CC</sub> = 400V	
E <sub>on</sub>	Turn-On Switching Loss	—	625	1141	μJ	I <sub>C</sub> = 48A, V <sub>CC</sub> = 400V, V <sub>GE</sub> = 15V	CT4
E <sub>off</sub>	Turn-Off Switching Loss	—	1275	1481		R <sub>G</sub> = 10Ω, L = 200μH, L <sub>S</sub> = 150nH, T <sub>J</sub> = 25°C	
E <sub>total</sub>	Total Switching Loss	—	1900	2622		Energy losses include tail & diode reverse recovery	
t <sub>d(on)</sub>	Turn-On delay time	—	60	78	ns	I <sub>C</sub> = 48A, V <sub>CC</sub> = 400V, V <sub>GE</sub> = 15V	CT4
t <sub>r</sub>	Rise time	—	40	56		R <sub>G</sub> = 10Ω, L = 200μH, L <sub>S</sub> = 150nH, T <sub>J</sub> = 25°C	
t <sub>d(off)</sub>	Turn-Off delay time	—	145	176			
t <sub>f</sub>	Fall time	—	35	46			
E <sub>on</sub>	Turn-On Switching Loss	—	1625	—	μJ	I <sub>C</sub> = 48A, V <sub>CC</sub> = 400V, V <sub>GE</sub> = 15V	13, 15
E <sub>off</sub>	Turn-Off Switching Loss	—	1585	—		R <sub>G</sub> = 10Ω, L = 200μH, L <sub>S</sub> = 150nH, T <sub>J</sub> = 175°C ④	CT4
E <sub>total</sub>	Total Switching Loss	—	3210	—		Energy losses include tail & diode reverse recovery	WF1, WF2
t <sub>d(on)</sub>	Turn-On delay time	—	55	—	ns	I <sub>C</sub> = 48A, V <sub>CC</sub> = 400V, V <sub>GE</sub> = 15V	14, 16
t <sub>r</sub>	Rise time	—	45	—		R <sub>G</sub> = 10Ω, L = 200μH, L <sub>S</sub> = 150nH	CT4
t <sub>d(off)</sub>	Turn-Off delay time	—	165	—		T <sub>J</sub> = 175°C	WF1
t <sub>f</sub>	Fall time	—	45	—			WF2
C <sub>ies</sub>	Input Capacitance	—	3025	—	pF	V <sub>GE</sub> = 0V	23
C <sub>oes</sub>	Output Capacitance	—	245	—		V <sub>CC</sub> = 30V	
C <sub>res</sub>	Reverse Transfer Capacitance	—	90	—		f = 1.0Mhz	
RBSOA	Reverse Bias Safe Operating Area	FULL SQUARE				T <sub>J</sub> = 175°C, I <sub>C</sub> = 192A V <sub>CC</sub> = 480V, V <sub>p</sub> = 600V R <sub>G</sub> = 10Ω, V <sub>GE</sub> = +15V to 0V	4 CT2
SCSOA	Short Circuit Safe Operating Area	5	—	—	μs	V <sub>CC</sub> = 400V, V <sub>p</sub> = 600V R <sub>G</sub> = 10Ω, V <sub>GE</sub> = +15V to 0V	22, CT3 WF4
E <sub>rec</sub>	Reverse Recovery Energy of the Diode	—	845	—	μJ	T <sub>J</sub> = 175°C	17, 18, 19
t <sub>rr</sub>	Diode Reverse Recovery Time	—	115	—	ns	V <sub>CC</sub> = 400V, I <sub>F</sub> = 48A	20, 21
I <sub>rr</sub>	Peak Reverse Recovery Current	—	40	—	A	V <sub>GE</sub> = 15V, R <sub>G</sub> = 10Ω, L = 200μH, L <sub>S</sub> = 150nH	WF3

**Notes:**

- ① V<sub>CC</sub> = 80% (V<sub>CE(S)</sub>), V<sub>GE</sub> = 20V, L = 200μH, R<sub>G</sub> = 10Ω.  
 ② This is only applied to TO-247AC package.

- ③ Pulse width limited by max. junction temperature.  
 ④ Refer to AN-1086 for guidelines for measuring V<sub>(BR)CES</sub> safely.